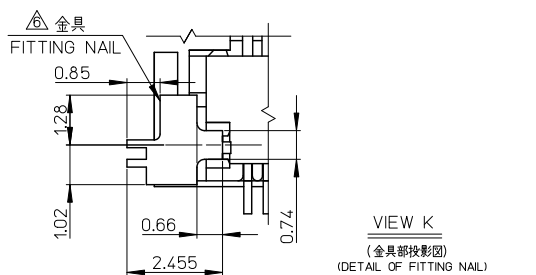
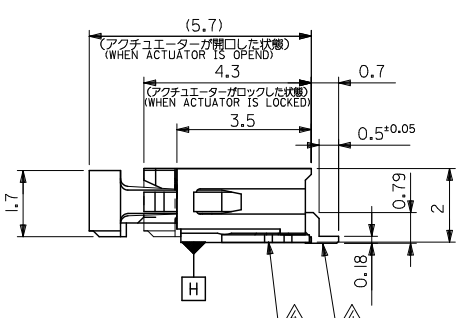
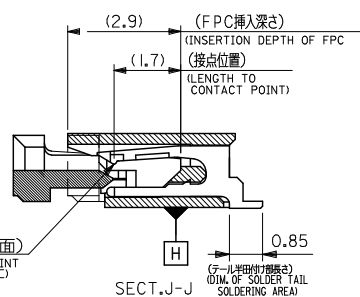
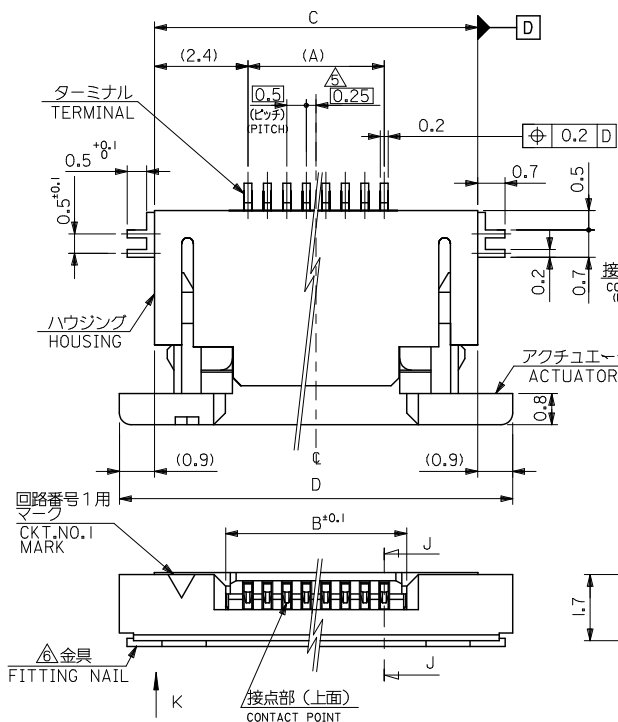


FOR LIMITED USE BY COMPAL ELECTRONICS,INC.



注記 NOTES

- 1.材質: MATERIAL**  
 ハウジング: 46ナイロン、ガラス充填、UL94V-0、白色  
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
 アクチュエータ: PPS、ガラス充填、UL94V-0、黒  
 ACTUATOR: PPS, GLASS FILLED, UL94V-0, BLACK  
 ターミナル: リン青銅 (t=0.2)  
 TERMINAL: PHOSPHOR BRONZE (t=0.2)  
 金具: リン青銅 (t=0.2)  
 FITTING NAIL: PHOSPHOR BRONZE (t=0.2)
- 2.めっき仕様: PLATING**  
 ターミナル: TERMINAL  
 接点部: 金メッキ 0.1μm以上  
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM  
 テール部: 金メッキ 0.05μm以上  
 TAIL AREA: GOLD 0.05 MICROMETER MINIMUM  
 下地めっき: ニッケル 1.0μm以上  
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM  
 金具: FITTING NAIL  
 無光沢めっき 1.0μm以上  
 PLATING MATTE TIN 1.0 MICROMETER MINIMUM  
 下地めっき: ニッケル 1.0μm以上  
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- 3.エンボスステップ梱包時は、アクチュエータがロックした状態になります。**  
 IN THE PACKAGE, ACTUATOR OF PART NO.52745-\*\*-59 SHOULD BE LOCKED.  
 ソルダータール半田付け面のスレ量、及び金具半田付け面のスレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.  
 UPPER DIRECTION: 0.1MAXIMUM  
 LOWER DIRECTION: 0.15 MAXIMUM
- △ 偶数極に適用**  
 APPLY FOR EVEN CIRCUIT.
- △ ハブターン剥離止め金具**  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.  
 R0.3は、FPCの胴体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
- 8.ELV 及び RoHS 適合品**  
 ELV AND RoHS COMPLIANT

16.1	14.3	10.65	9.5	52745-2090	20
D	C	B	(A)	EMBOSSED PACKAGE	極数
					CKT.
CONNECTOR SERIES NO. : 52745-**-17					

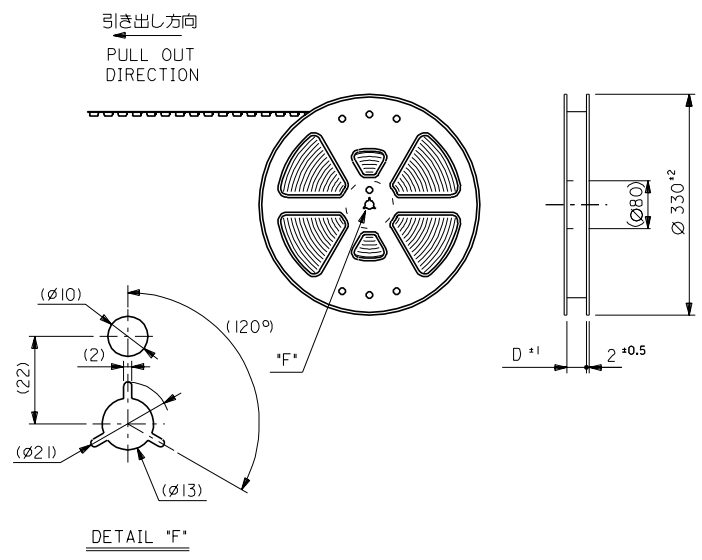
<b>RELEASED</b> EC NO: J2011-160 DRWN: KMIYAHARA 2011/03/11 CHYK: KAKAHASHI 2011/03/16 APPR: KMORI KAWA 2011/03/22 A REV:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KMIYAHARA	DATE 2011/03/11	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING		
	10 OVER 30 UNDER	±0.25	CHECKED BY KMIYAHARA	DATE 2011/03/16	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORI KAWA	DATE 2011/03/22	DOCUMENT NO. RSD-52745-088		
	ANGULAR ±3°		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

ib\_frame\_A3\_J\_ME\_S Rev. E 2006/04/15

EN-02JA(021)

DWC. NO. SD-52745-\*\*\*90

DIMENSIONS IN METRIC DO NOT SCALE DRAWING



5. 材料  
 キャリアテープ:ポリプロピレン (PP)  
 トップテープ:PET, PE, PEF  
 リール:ポリスチレン (PS) <リサイクル材を含む>

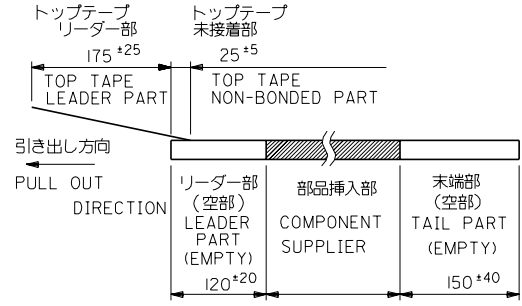
MATERIAL CARRIER TAPE:POLYPROPYLENE  
 TOP TAPE:PET,PE,PEF  
 REEL:POLYSTYRENE(PS)  
 <RECYCLE MATERIAL CONTAINED>

注記 NOTES

1. 製品番号 52745-\*\*\*17 の梱包状態はアクチュエータがロックした状態とする。  
 詳細寸法については図面 SD-52745-\*\*\*17 を参照下さい。  
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-\*\*\*17 SHOULD BE LOCKED  
 RE DETAILED DIMENSIONS,SEE SD-52745-\*\*\*17

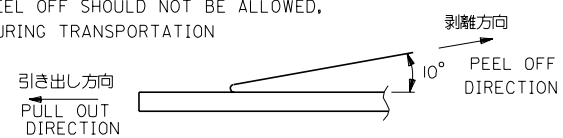
2. 梱包数量:1000個/リール  
 NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度:(剥離方向は下図参照)  
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE  
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION

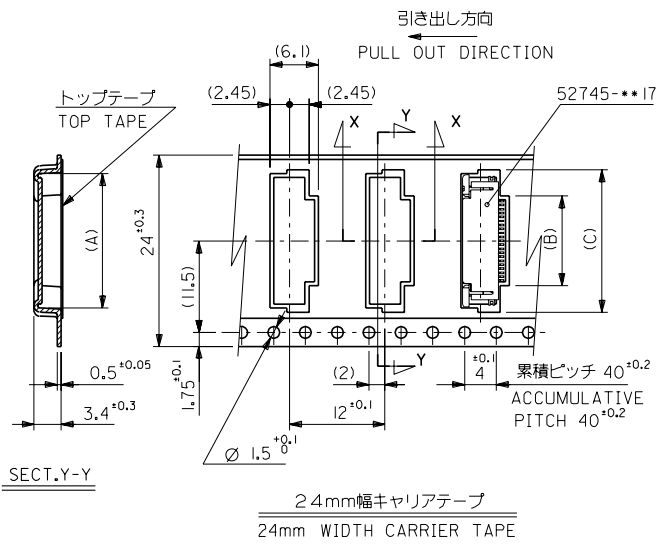


角度 ANGLE		130°				材料 MATERIAL	注記参照 SEE NOTES	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30以上 OVER	+0.2	B	変更 REVISIED (J402001-0425)	4/25	00/12/20	仕上げ FINISH	---	
10以上 未満 OVER 30 UNDER	+0.25	A	変更 REVISIED (J40949)	4/11	94/11/17	適用電線範囲 WIRE RANGE	---	TITLE 名称
10未満 UNDER	+0.2	O	新規発行 RELEASED (J40230)	5/25	94/3/24	被覆外径 INS. RANGE	---	0.5 FPC Conn ZIF SMT RA Upper Contact Embstp Pkg
一般公差 GENERAL TOLERANCES		記号 ITR	変更内容 REVISION RECORD	DR. CHK.	DATE	DRAWN BY:94/3/24 S.AIHARA	CHK'D BY:00/12/20 S.KUNISHI	DWG. NO. (SHEET 1 OF 3) REV B

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DWG. NO. SD-52745-\*\*\*90

DIMENSIONS IN METRIC DO NOT SCALE DRAWING



24	25.5	17.4	10.8	16.4	52745-2090	20
		16.9	10.3	15.9	-1990	19
		16.4	9.8	15.4	-1890	18
		15.9	9.3	14.9	-1790	17
		15.4	8.8	14.4	-1690	16
		14.9	8.3	13.9	-1590	15
		14.4	7.8	13.4	-1490	14
		13.9	7.3	12.9	-1390	13
		13.4	6.8	12.4	-1290	12
		12.9	6.3	11.9	-1190	11
		12.4	5.8	11.4	-1090	10
		11.9	5.3	10.9	-0990	9
		11.4	4.8	10.4	-0890	8
10.9	4.3	9.9	-0790	7		
10.4	3.8	9.4	52745-0690	6		
キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	極数 CIRCUIT
		ENG. NO.				

角度 ANGLE	130°				材料 MATERIAL	
30以上 OVER	+0.5	B	変更 REVISED	UC2001-0425	SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3	
10以上 未過	+0.25	A	変更 REVISED	J409491	仕上げ FINISH	
10未満	+0.2	O	新規/再 RELEASED	J40230	適用電線範囲 WIRE RANGE	
一般公差 GENERAL TOLERANCES					被覆外径 INS. RANGE	
記号 LTR			変更内容 REVISION RECORD	DR.	DATE	DATE
				CHK.		

**MOLEX-JAPAN CO.,LTD.**  
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

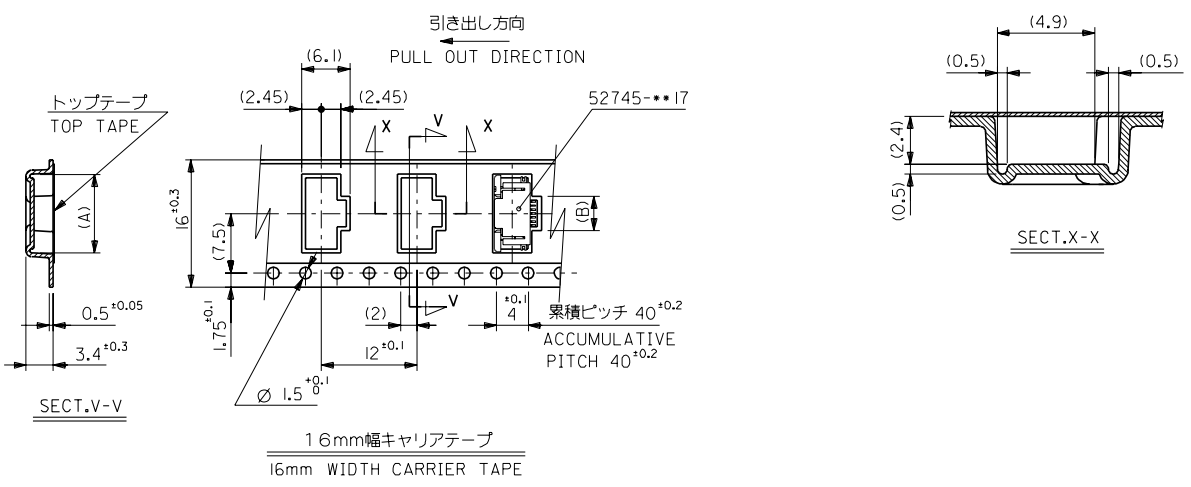
TITLE 名称  
0.5 FPC Conn ZIF SMT RA  
Upper Contact  
Embstp Pkg

DWG. NO. (SHEET 2 OF 3) REV  
SD-52745-\*\*\*90 B

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EN-01C(032)MXJ-32

DWG. NO. SD-52745-\*\*\*90

DIMENSIONS IN METRIC DO NOT SCALE DRAWING



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH				ENG. NO.	極数 CIRCUIT

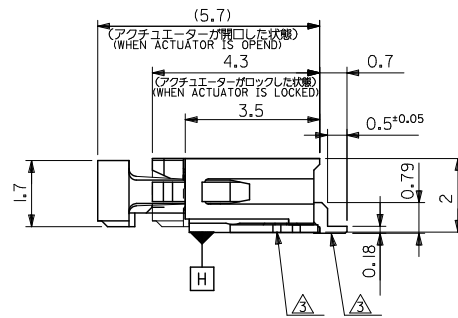
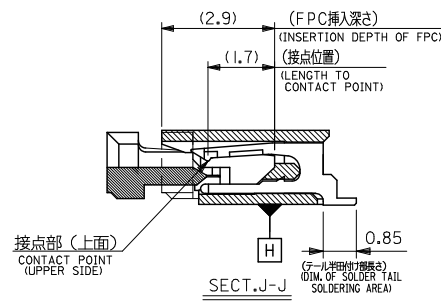
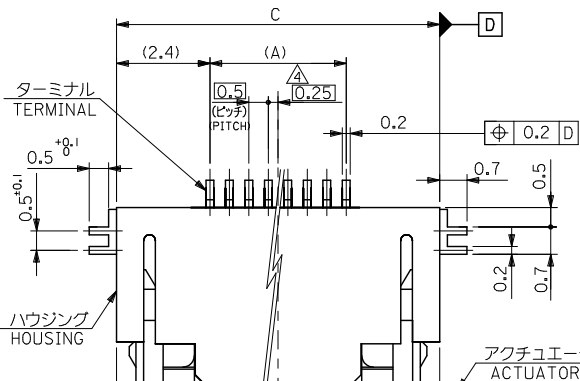
材料 MATERIAL	
SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3	
仕上げ FINISH	—
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '98/3/24 S. AIHARA	CHK'D BY '00/12/20 S. KUNISHI
APP'D BY '00/12/20 M. FUKUSHIMA	尺度 SCALE

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社			
REVISION RECORD			
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	DATE DATE
TITLE 名称 0.5 FPC Conn ZIF SMT RA Upper Contact Embstp Pkg			
DWG. NO. (SHEET 3 OF 3) REV SD-52745-***90 B			

角度 ANGLE	130°
30以上 OVER	+0.05
10以上 30 UNDER	+0.15
未過 10 UNDER	+0.2
一般公差 GENERAL TOLERANCES	

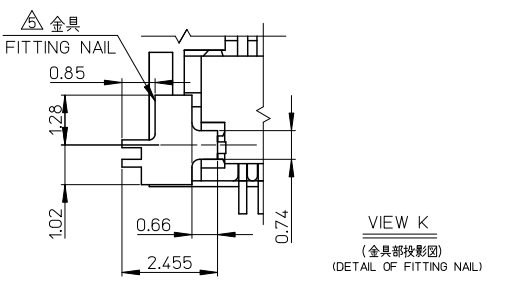
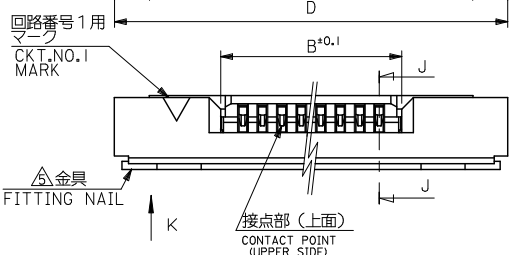
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX/JAPAN AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION  
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10 9 8 7 6 5 4 3 2 1

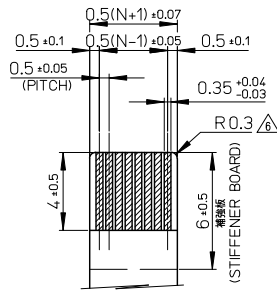


16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
15.1	13.3	9.65	8.5	52745-1890	18
14.6	12.8	9.15	8	52745-1790	17
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
13.1	11.3	7.65	6.5	52745-1490	14
12.6	10.8	7.15	6	52745-1390	13
12.1	10.3	6.65	5.5	52745-1290	12
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オートナー番	極数 CKT.

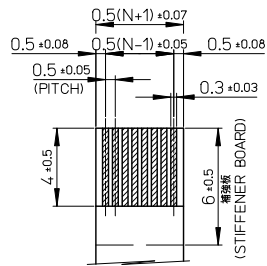
CONNECTOR SERIES NO. : 52745-\*\*\*17



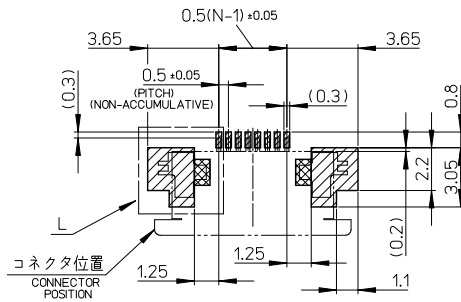
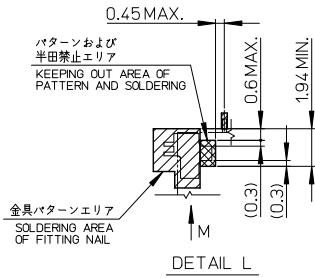
REVISED EEC NO: J2011-0041 T: DRW:HYOSHINO 2010/07/08 CHYKDHII J IMA 2010/07/08 APPR: KMORI KAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING		
	10 OVER 30 UNDER	± 0.25	CHECKED BY SKUNISHI	DATE 2000/06/30	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY KMORI KAWA	DATE 2010/07/16	DOCUMENT NO. SD-52745-054		
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	SHEET NO. 1 OF 2		
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



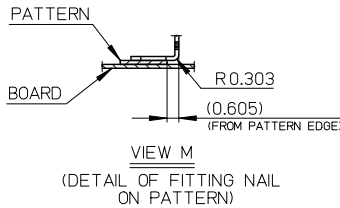
適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト  
 (マウント面)  
 RECOMMENDED P.C.BOARD  
 PATTERN DIMENSION(REF.)  
 (MOUNTING SIDE)



注記NOTES

1. 使用材料  
 MATERIAL  
 ハウジング: 46ナイロン, ガラス充填, UL94V-0, 白  
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
 アクチュエータ: ポリフェニレンサルファイド (PPS), ガラス充填, UL94V-0, 黒  
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK  
 ターミナル: リン青銅, 銅下地半田めっき (±0.2)  
 TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING  
 金具: リン青銅, 銅下地半田めっき (±0.2)  
 FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
  2. エンボステープ梱包時は、アクチュエータがロックした状態になります。  
 IN THE PACKAGE, ACTUATOR OF PART NO.52745-xx\*17 SHOULD BE LOCKED.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.  
 UPPER DIRECTION: 0.1MAXIMUM  
 LOWER DIRECTION: 0.15 MAXIMUM
- △ 偶数極に適用  
 APPLY FOR EVEN CIRCUIT.
- △ ハターン剥離止め金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
- △ R0.3は、FPCの胴体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて:

打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL : STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED IEC NO: J2011-0041 T: DRW: HYO SHINO 2010/07/08 CHY: KISHI JI MA 2010/07/08 APPR: KORI KAWA 2010/07/16 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING		
	10 OVER 30 UNDER	± ---	CHECKED BY SKUNISHI	DATE 2000/06/30	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY KORI KAWA	DATE 2010/07/16	DOCUMENT NO. SD-52745-054	SHEET NO. 2 OF 2	
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	